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[Samsung Electro-Mechanics America, Inc.](#)
[CL32F106ZAHNNNE](#)

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SAMSUNG
ELECTRO-MECHANICS



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL32F106ZAHNNNE**
- Description : **CAP, 10 μ F, 25V, -20/+80%, Y5V, 1210**

A. Samsung Part Number

CL 32 F 106 Z A H N N N E
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor				
② Size	1210 (inch code)	L: 3.2 \pm 0.3 mm	W: 2.5 \pm 0.2 mm		
③ Dielectric	Y5V	⑧ Inner electrode	Ni		
④ Capacitance	10 μ F	Termination	Cu		
⑤ Capacitance tolerance	-20/+80 %	Plating	Sn 100% (Pb Free)		
⑥ Rated Voltage	25 V	⑨ Product	Normal		
⑦ Thickness	1.6 \pm 0.2 mm	⑩ Special	Reserved for future use		
		⑪ Packaging	Embossed Type, 7" reel		

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1kHz \pm 10% 1.0 \pm 0.2Vrms
Tan δ (DF)	0.09 max.	
Insulation Resistance	10,000Mohm or 100Mohm $\cdot\mu$ F Whichever is Smaller	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (\times 10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characterisitcs	Y5V (From -30 $^{\circ}$ C to 85 $^{\circ}$ C, Capacitance change shoud be within -82~+22%)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g \cdot F, for 10 \pm 1 sec.
Bending Strength	Capacitance change : within \pm 30%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245 \pm 5 $^{\circ}$ C, 3 \pm 0.3sec. (preheating : 80~120 $^{\circ}$ C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within \pm 20% Tan δ , IR : initial spec.	Solder pot : 270 \pm 5 $^{\circ}$ C, 10 \pm 1sec.

	Performance	Test condition
Vibration Test	Capacitance change : within $\pm 20\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours \times 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within $\pm 30\%$ Tan δ : 0.125 max IR : 500Mohm or 25Mohm $\cdot \mu F$ Whichever is Smaller	With rated voltage 40 \pm 2 $^{\circ}$ C, 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within $\pm 30\%$ Tan δ : 0.125 max IR : 1000Mohm or 50Mohm $\cdot \mu F$ Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within $\pm 20\%$ Tan δ , IR : initial spec.	1 cycle condition Min. operating temperatur \rightarrow 25 $^{\circ}$ C \rightarrow Max. operating temperature \rightarrow 25 $^{\circ}$ C 5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.